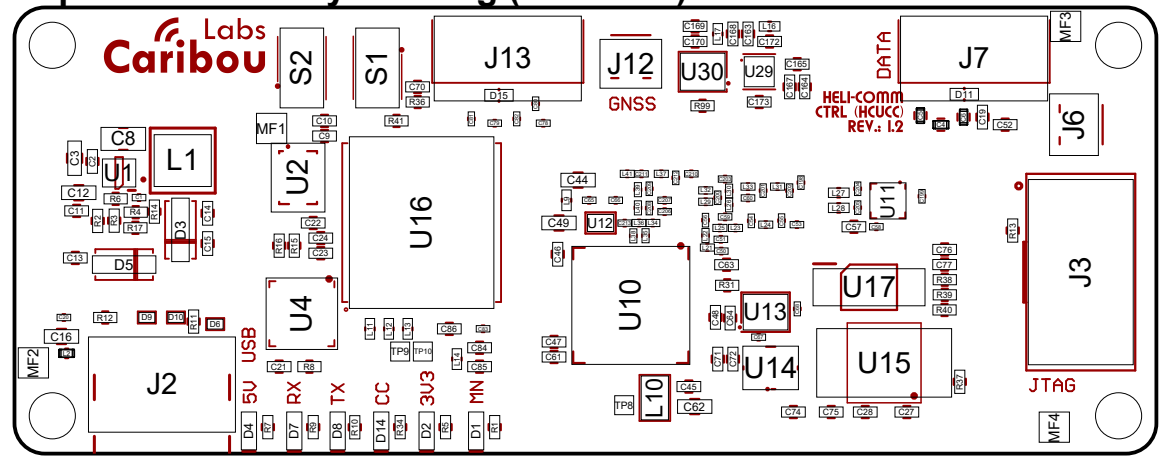
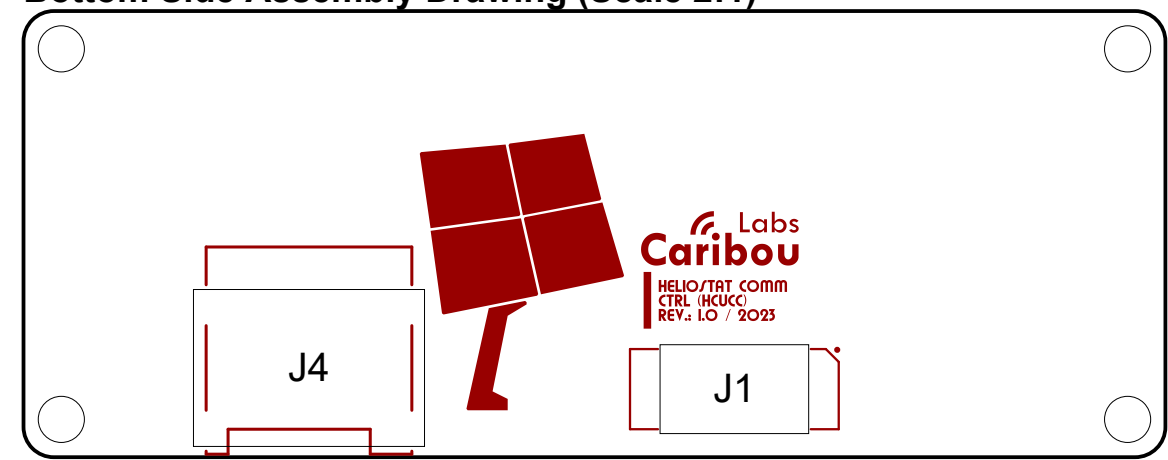


ASSEMBLY DRAWING

Top Side Assembly Drawing (Scale 2:1)



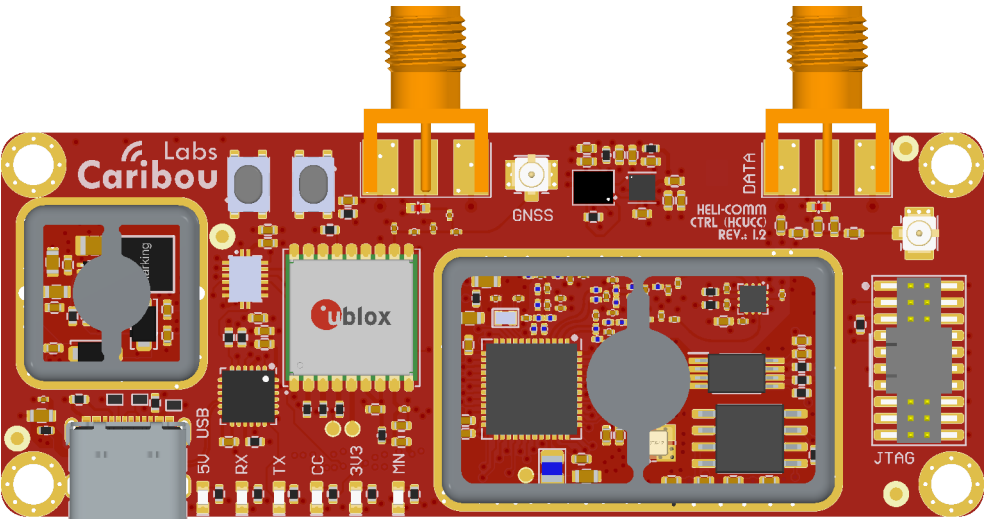
Bottom Side Assembly Drawing (Scale 2:1)



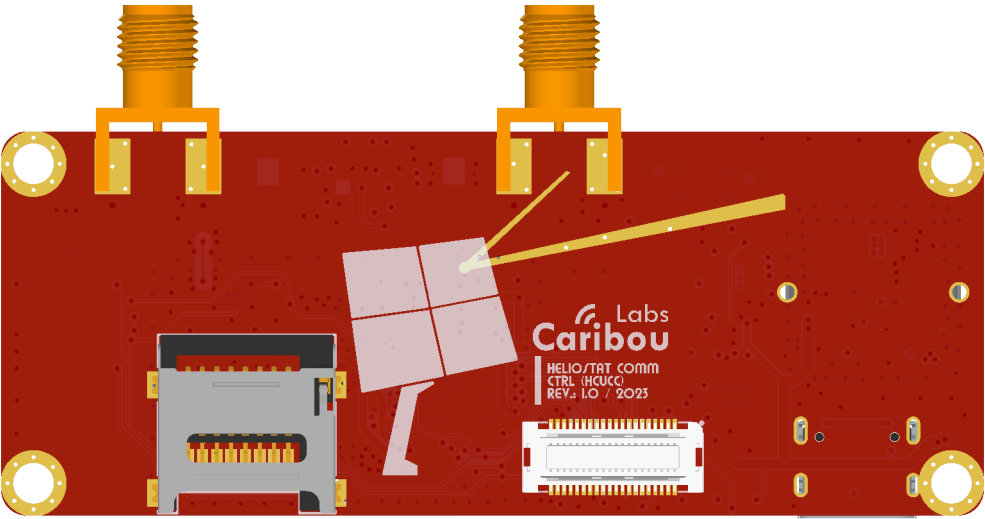
<div><div>Labs</div><div>Caribou</div></div>				TITLE	
				P/N =BoardAssyPN	
	ID/SIG.			DATE	
DESIGNED					
CHECKED	=Checker				
Q.A.					
CLASS =Class	SIZE =Size	DRAW No. =DrawingNum	SHEET AD=Sheet	OF =TotalShe	REV

BOARD REALISTIC VIEW

TOP



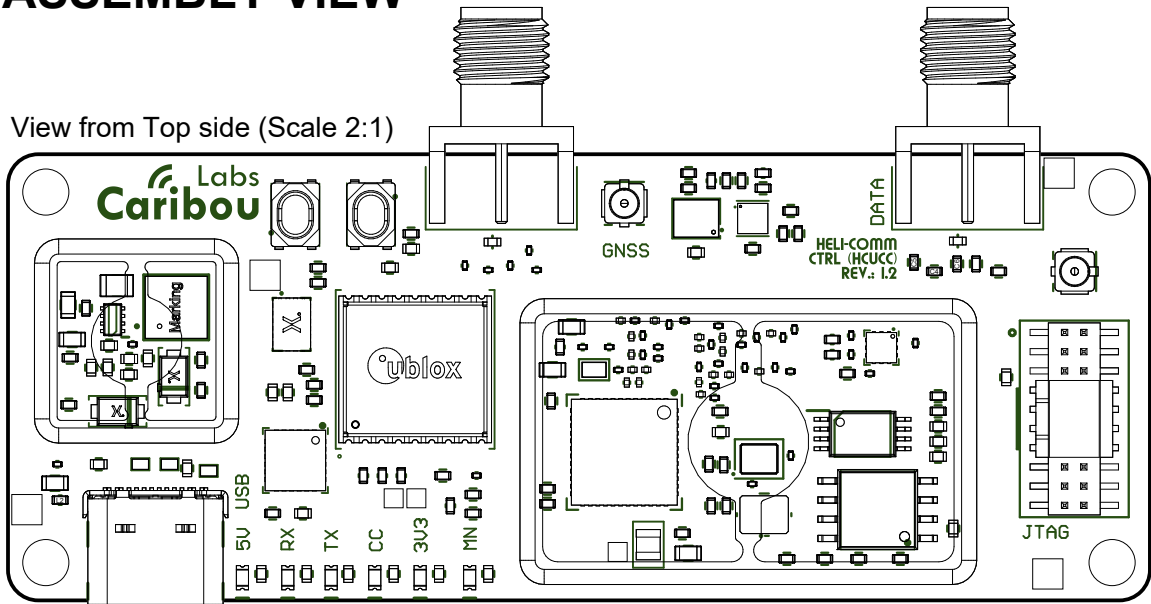
BOTTOM



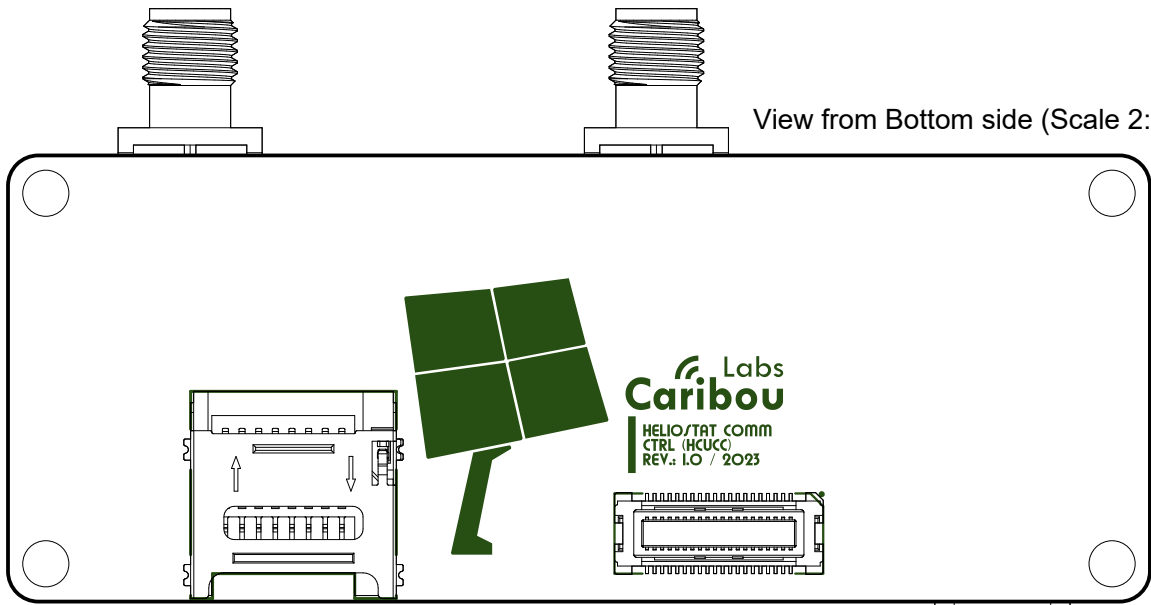
<div>Labs Caribou</div>				TITLE	
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	ID/SIG.			DATE	
DESIGNED					
CHECKED	=Checker				
Q.A.					
CLASS =Class	SIZE =Size	DRAW No. =DrawingNum	SHEET AD=Sheet	OF =TotalShe	REV

ASSEMBLY VIEW

View from Top side (Scale 2:1)



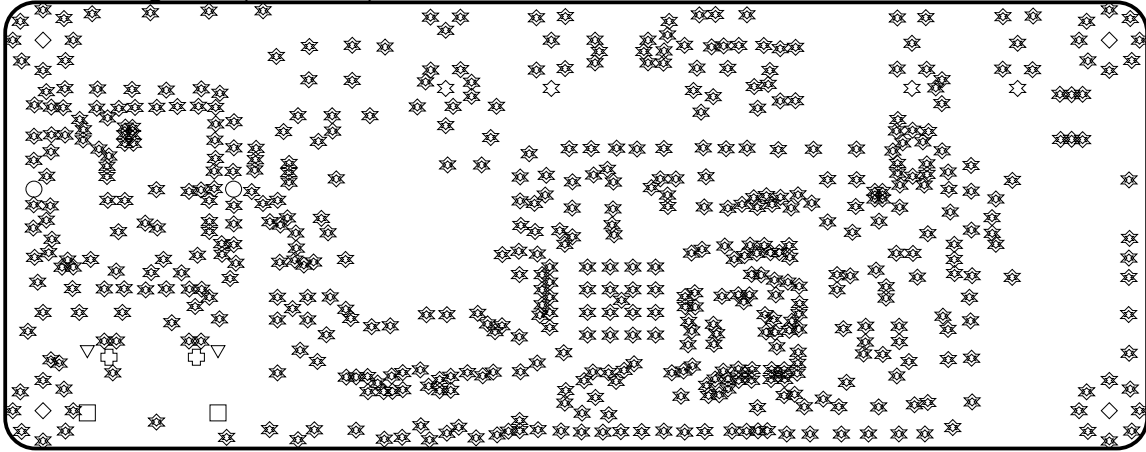
View from Bottom side (Scale 2:1)



<div><div>Labs</div><div>Caribou</div></div>	TITLE			
P/N				=BoardAssyPN
ID/SIG.				DATE
DESIGNED				
CHECKED	=Checker			
Q.A.				
CLASS	SIZE	DRAW No.	SHEET	OF
=Class	=Size	=DrawingNum	AD=Sheet	=TotalShe
				REV




Drill Drawing View (Scale 2:1)




Drill Table

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Length
✳	560	0.305mm	Plated	Round	Component Side - Bottom Layer	
☆	4	0.460mm	Plated	Round	Component Side - Bottom Layer	
□	2	0.600mm	Plated	Slot	Component Side - Bottom Layer	1.400mm
▽	2	0.600mm	Plated	Slot	Component Side - Bottom Layer	1.700mm
⊕	2	0.650mm	Non-Plated	Round	Component Side - Bottom Layer	
○	2	1.100mm	Plated	Round	Component Side - Bottom Layer	
◇	4	3.100mm	Plated	Round	Component Side - Bottom Layer	
576 Total						

<div></div>		TITLE	
		P/N	=BoardAssyPN
	ID/SIG.		DATE
DESIGNED			
CHECKED	=Checker		
Q.A.			
CLASS =Class	SIZE =Size	DRAW No. =DrawingNum	SHEET AD=Sheet   OF =TotalShe
		REV	

Layer Stack Legend


	Material	Layer	Thickness	Dielectric	Material	Type	Gerber
		Top Overlay				Legend	GTO
	Surface Material	Top Solder	0.025mm	White		Solder Mask	GTS
	Copper	Component Side	0.035mm			Signal	GTL
	Prepreg		0.110mm	PrePreg		Dielectric	
	Copper	Layer 1	0.036mm			Signal	G1
	Core		0.305mm	FR-4		Dielectric	
	Copper	Layer 2	0.036mm			Signal	G2
			0.508mm	PrePreg		Dielectric	
	Copper	Layer 3	0.036mm			Signal	G3
	Core		0.305mm	FR-4		Dielectric	
	Copper	Layer 4	0.036mm			Signal	G4
	Prepreg		0.110mm	PrePreg		Dielectric	
	Copper	Bottom Layer	0.035mm			Signal	GBL
	Surface Material	Bottom Solder	0.025mm	White		Solder Mask	GBS
		Bottom Overlay				Legend	GBO

		TITLE	
		P/N	=BoardAssyPN
	ID/SIG.		DATE
DESIGNED			
CHECKED	=Checker		
Q.A.			
CLASS =Class	SIZE =Size	DRAW No. =DrawingNum	SHEET OF AD=Sheet   =TotalShe
		REV	

IMPEDANCE CONTROL TABLE:

Transmission Line Structure Table

Impedance Id	Transmission Line	Target Impedance	Trace layer	Lower Trace Width	Upper Trace Width	Gap	Reference layers
1	Coated Microstrip	50	Component Side	0.1686mm	0.1686mm		Layer 1
2	Edge-Coupled Coated Microstrip	90	Component Side	0.1720mm	0.1720mm	0.1270mm	Layer 1
3	Coated Microstrip	50	Bottom Layer	0.1686mm	0.1686mm		Layer 4
4	Edge-Coupled Coated Microstrip	90	Bottom Layer	0.1720mm	0.1720mm	0.1270mm	Layer 4

				TITLE	
				P/N =BoardAssyPN	
	ID/SIG.			DATE	
DESIGNED					
CHECKED	=Checker				
Q.A.					
CLASS =Class	SIZE =Size	DRAW No. =DrawingNum	SHEET AD=Sheet	OF =TotalShe	REV